

PATENT ABSTRACTS OF JAPAN

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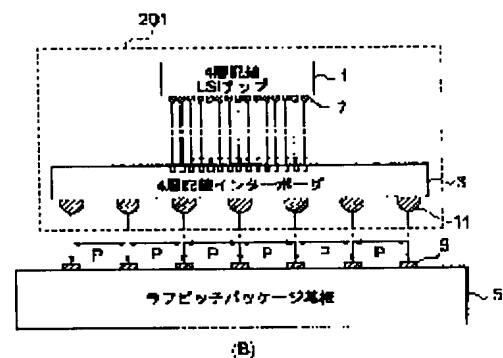
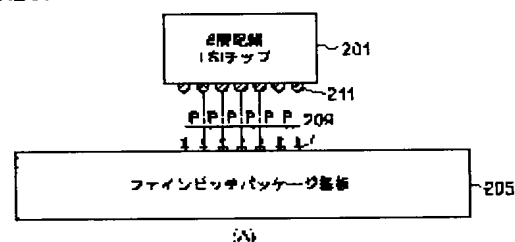
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(54) SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND MANUFACTURING METHOD THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor integrated circuit device capable of reducing the production cost.

SOLUTION: A semiconductor integrated circuit board includes a semiconductor integrated circuit chip 1, an interposer joined electrically to the semiconductor integrate circuit chip 1, and a package substrate 5 joined electrically to the interposer. In this case, the number of wiring layers on the semiconductor integrate circuit chip 1 is reduced, and the function of the wiring layer is transferred to the interposer 3.



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